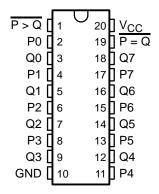
SCLS018D - MARCH 1984 - REVISED MARCH 2003

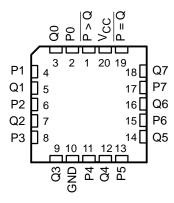
- Wide Operating Voltage Range of 2 V to 6 V
- High-Current Outputs Drive Up To 10 LSTTL Loads
- Typical t_{pd} = 22 ns

SN54HC682...J OR W PACKAGE SN74HC682...DW OR N PACKAGE (TOP VIEW)



- ±4-mA Output Drive at 5 V
- Compare Two 8-Bit Words
- 100-kΩ Pullup Resistors Are on the Q Inputs

SN54HC682 . . . FK PACKAGE (TOP VIEW)



description/ordering information

These magnitude comparators perform comparisons of two 8-bit binary or BCD words. The 'HC682 devices feature $100-k\Omega$ pullup termination resistors on the Q inputs for analog or switch data.

ORDERING INFORMATION

TA	PACK	AGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube	SN74HC682N	SN74HC682N
–40°C to 85°C	SOIC - DW	Tube	SN74HC682DW	HC682
	30IC - DVV	Tape and reel	SN74HC682DWR	ПС002
	CDIP – J	Tube	SNJ54HC682J	SNJ54HC682J
–55°C to 125°C	CFP – W	Tube	SNJ54HC682W	SNJ54HC682W
	LCCC – FK	Tube	SNJ54HC682FK	SNJ54HC682FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

DATA	OUTPUTS					
INPUTS P, Q	$\overline{P} = Q$ $\overline{P} > Q$					
P = Q	L	Н				
P > Q	Н	L				
P < Q	I н	Н				

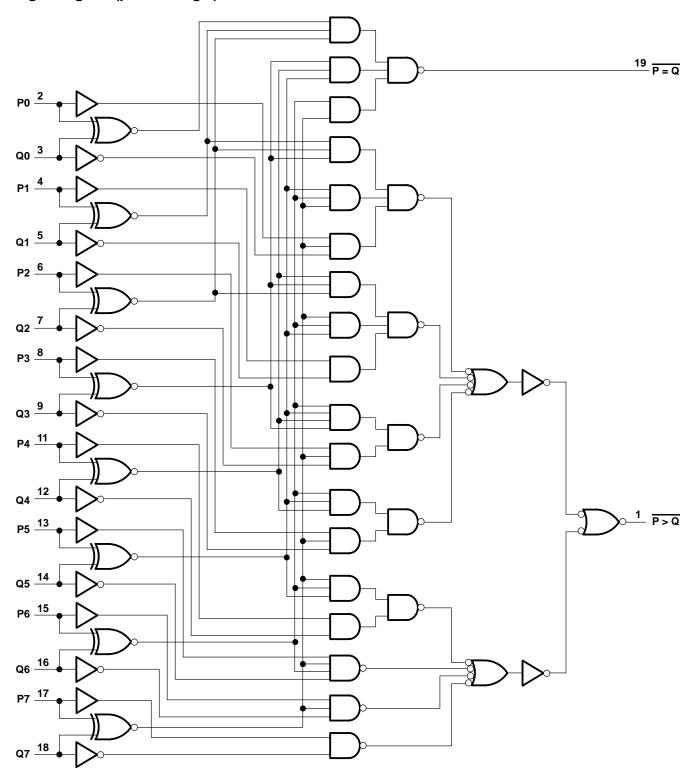
The $\overline{P} < \overline{Q}$ function can be generated by applying $\overline{P} = \overline{Q}$ and $\overline{P} > \overline{Q}$ to a 2-input NAND gate.



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logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{CC}) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2): DW package	58°C/W
N package	69°C/W
Storage temperature range, T _{sto}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions (see Note 3)

			SN	154HC68	32	SN	174HC68	2	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNII
Vcc	Supply voltage		2	5	6	2	5	6	V
		V _{CC} = 2 V	1.5			1.5			
ViH	High-level input voltage	V _{CC} = 4.5 V	3.15		7	3.15			V
		V _{CC} = 6 V	4.2		<.	4.2			
		V _{CC} = 2 V		JY.	0.5			0.5	
\vee_{IL}	Low-level input voltage	V _{CC} = 4.5 V		2	1.35			1.35	V
		V _{CC} = 6 V		Q	1.8			1.8	
٧ _I	Input voltage		0		VCC	0		VCC	V
۷o	Output voltage		0		VCC	0		VCC	V
		V _{CC} = 2 V			1000			1000	
t _t	Input transition (rise and fall) time	V _{CC} = 4.5 V			500			500	ns
		V _{CC} = 6 V			400			400	
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

^{2.} The package thermal impedance is calculated in accordance with JESD 51-7.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST C	ONDITIONS	Vaa	Т	A = 25°C	;	SN54F	IC682	SN74H	IC682	UNIT	
PARAMETER	lesi Co	CNUTTIONS	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	ONIT	
			2 V	1.9	1.998		1.9		1.9			
		$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4			
Vон	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V	
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84			
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2	:h	5.34			
			2 V		0.002	0.1		0.1		0.1		
		$I_{OL} = 20 \mu A$	4.5 V		0.001	0.1		0.1		0.1		
V_{OL}	$V_I = V_{IH}$ or V_{IL}		6 V		0.001	0.1	, C	0.1		0.1	V	
		I _{OL} = 4 mA	4.5 V		0.17	0.26	20	0.4		0.33		
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26	08/	0.4		0.33		
l _{IH}	$V_I = V_{CC}$		6 V		0.1	100	y	1000		1000	nA	
1	\/ ₁ 0	Q inputs	6 V		-50	-90		-160		-140	μΑ	
IIL	V _I = 0	All other inputs	6 V		-0.1	-100		-1000		-1000	nA	
ICC	$V_I = V_{CC}$ or 0,	IO = 0	6 V		480	700		1300		1100	μΑ	
C _i			2 V to 6 V		3	10		10		10	pF	

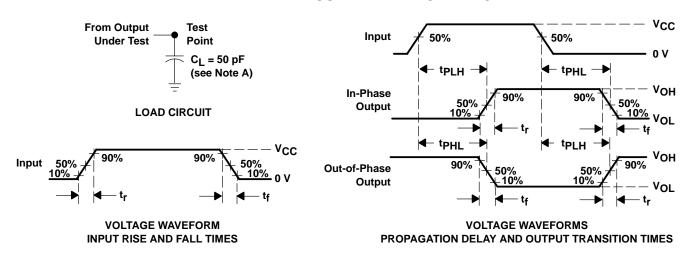
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	то	V	T,	\ = 25°C	;	SN54F	IC682	SN74H	IC682	UNIT
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNII
			2 V		130	275		413		344	
^t pd	P or Q	Any	4.5 V		26	55		88		69	ns
			6 V		22	47	\ \ \ \	70		58	
			2 V		38	75	3	110		95	
t _t		Any	4.5 V		8	15	90	22		19	ns
			6 V		6	13	y d	19		16	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance	No load	40	pF

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \ \Omega$, $t_f = 6 \ ns$, $t_f = 6 \ ns$.
- C. The outputs are measured one at a time with one input transition per measurement.
- D. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGE OPTION ADDENDUM

10-Dec-2020

PACKAGING INFORMATION

www.ti.com

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC682DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC682	Samples
SN74HC682DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC682	Samples
SN74HC682N	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	-40 to 85	SN74HC682N	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

10-Dec-2020

In no event shall TI's liabilit	y arising out of such information	exceed the total purchase	price of the TI part(s) a	at issue in this document sold by	TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

14-Jul-2012 www.ti.com

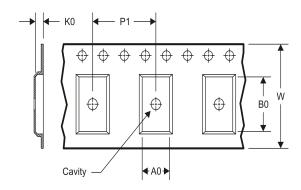
TAPE AND REEL INFORMATION

REEL DIMENSIONS





TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC682DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 14-Jul-2012



*All dimensions are nominal

ĺ	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
I	SN74HC682DWR	SOIC	DW	20	2000	367.0	367.0	45.0	

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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